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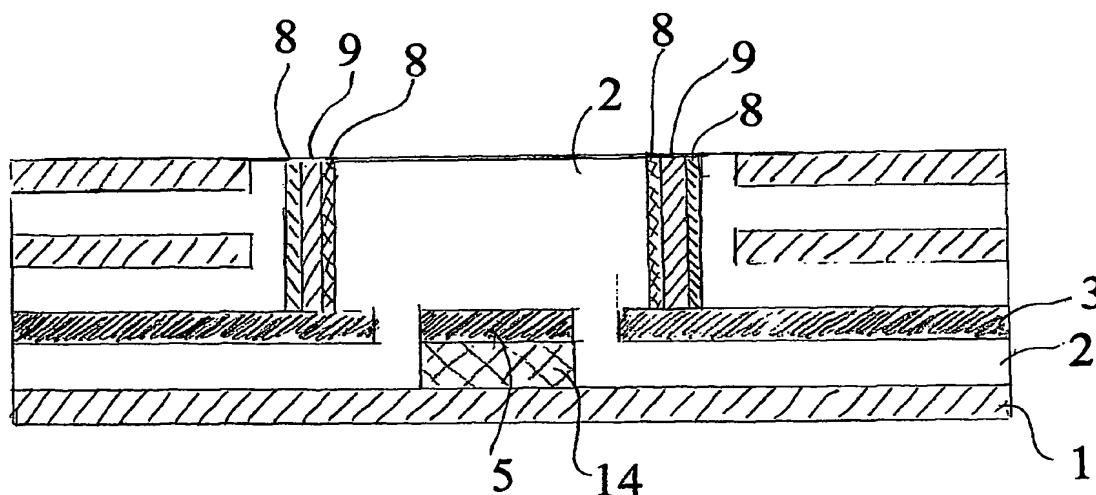
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(54) Title: METHOD FOR CONSTRUCTING EMI SHIELDING AROUND A COMPONENT EMBEDDED IN A CIRCUIT
BOARD



(57) Abstract: The invention relates to a method for constructing EMI shielding around a component embedded in a circuit board. According to the method, a recess, which is extended to an insulating layer that represents the ground-reference plane, is formed around the embedding location of the component. The recess is filled or surfaced with an electrically conductive material, in such a way that the material is in electrical contact with the ground-reference plane and that the material essentially surrounds the component in the direction of the circuit board.